

## Key Features

Adheres to Dissimilar Materials  
Self Leveling  
Hydrolytic Stability  
High Temperature Resistant  
Low Shrinkage  
Non-hazardous per D.O.T. Regulations

## Uncured

Pot Life @ 25°C: 2 hours  
Viscosity @ 25°C: 5,000 cPs  
Shelf Life @ -40°C: 6 Months

## Cure Options

1 hour @ 92°C  
4 hours @ 65°C  
48 hours @ 25°C

## Cured Properties

(Based on cure of 4 hours @ 65°C)

Color	Black
Shore D Hardness	80
Density (g/cc)	1.07
Glass Transition Temp (°C)	45
Shrinkage Linear (%)	0.26

## Electrical Properties

(Based on cure of 4 hours @ 65°C)

Dielectric Constant	3.2 @ 1 kHz
Dissipation Factor	0.008 @ 1 kHz
Volume Resistivity (ohm-cm)	7.0E 13 @ 500 VDC

## Product Description:

5108 is a one part, black, electrically isolating, precision mixed, degassed, and frozen epoxy compound specifically designed for potting and sealing electronic components. 5108 is a self leveling material that exhibits low shrinkage once cured and can withstand high temperatures and high humidity or wet environments. This material is also environmentally friendly and considered non-hazardous per D.O.T. regulations.

## Thermal Properties

(Based on cure of 4 hours @ 65°C)

Glass Transition Temp (°C)	45
Degradation Temp. (°C)	275

## Outgassing Properties

(Based on cure of 4 hours @ 65°C)

TML (%)	0.75
CVCM (%)	0.01
WVR (%)	0.39

## Acoustic Properties

Velocity (m/s)	2,345
Impedance (MRayles)	2.51
Loss (dB/cm-MHz)	-4.83
Density (g/cc)	1.07

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